राष्ट्रीय प्रौद्योगिकी संस्थान मिजोरम NATIONAL INSTITUTE OF TECHNOLOGY MIZORAM

(An Institute of National Importance under Ministry of Education, Govt. of India) Chaltlang, Aizawl, Mizoram – 796012



Course Structure & Syllabus for M. Tech Programme in Microelectronics and VLSI System Design <u>BATCH : 2019-20 onwards</u>

सूक्ष्म कणिका एवं संचार अभियांत्रिकी विभाग Department of Electronics & Communication Engineering

Classification of Credits Points:

1 Hr Lecture (L) per week	1 Hr Tutorial (T) per week	1 Hr Laboratory (P) per week
2 Credits	2 Credits	1 Credit

Semester I				
Course Code	Course Name	Category	L-T-P	Credit
ECL 2101	Physics of Semiconductor Devices	DC	3-0-0	6
ECL 2102	Analog VLSI Circuits	DC	3-0-0	6
ECL 21XX	Elective I	DC	3-0-0	6
ECL 2104	Digital VLSI Circuits	DC	3-0-0	6
ECL 2105	Semiconductor Device Modeling	DC	3-0-0	6
ECP 2101	Analog VLSI Circuits Lab	DC	0-0-3	3
ECP 2102	Seminar	DC	0-0-2	2
TOTAL CREDITS				35

Semester II				
Course Code	Course Name	Category	L-T-P	Credit
ECL 2201	VLSI Physical Design	DC	3-0-0	6
ECL 2202	IC Technology	DC	3-0-0	6
ECL 2203	VLSI Testing and Verification	DC	3-0-0	6
ECL 22XX	Elective II	DC	3-0-0	6
ECP 2201	Digital VLSI Circuits Lab	DC	0-0-3	3
ECP 2202	Device and Process Modeling Lab	DC	0-0-3	3
ECP 2203	VLSI System Design Lab	DC	0-0-4	4
ECP 2204	Term Paper	DC	0-0-3	3
TOTAL CRED	ITS			37

Semester III					
Course Code	Course Name	Category	L-T-P	Credit	
ECP 2301	Project Phase I	DC	0-0-16	16	
TOTAL CREDITS				16	

Semester IV					
Course Code	Course Name	Category	L-T-P	Credit	
ECP 2401	Project Phase II	DC	0-0-24	24	
TOTAL CREDITS			24		

SEMESTER WISE CREDIT POINT(s)

Semester	Semester I	Semester II	Semester III	Semester IV	TOTAL
Credits	35	37	16	24	112

M.Tech Programme in Microelectronics & VLSI System Design: Course Structure & Syllabus

S1. No.	Course Code	Course Name
1	21XX/22XX	Mixed Signal VLSI Design
2	21XX/22XX	Low Power VLSI Design
3	21XX/22XX	MEMS and Microsystems
4	21XX/22XX	VLSI Architecture for DSP
5	21XX/22XX	Embedded Systems
6	21XX/22XX	RF IC Design
7	21XX/22XX	Nano-and-Molecular Electronics

ELECTIVES

Syllabus of First Semester

ECL 2101 Physics of Semiconductor Devices	
L-T-P: 3-0-0	Credits: 6
1. Introduction: Review of Semiconductor Devices, Carrier Statistics, Basic Crystal Structure, Valence Bonds, Energy Bands.	10 Lectures
2. Semiconductors in Equilibrium and Carrier Transport in Semiconductors: Semiconductor Materials, Carrier Concentration, Carrier Drift, Carrier Diffusion, Generation and Recombination Process, Continuity Equation, Thermionic Emission, Tunneling, Ballistic Transport, High Field Effects.	8 Lectures
3. Physics of Junction Devices: Thermal Equilibrium Condition, Depletion Region, Depletion and Diffusion Capacitances, Current-Voltage Characteristics, Charge Storage and Transient Behavior, Junction Breakdown, Metal Semiconductor Contacts, Optoelectronics devices.	10 Lectures
4. Physics of Bipolar devices: Transistor Action, Static Characteristics, Frequency Response and Switching, Heterojunction.	6 Lectures
5. Metal-semiconductor & Fundamentals of MOS and Field effect Devices: MOS Capacitor, MOSFET Fundamentals, MOSFET Scaling, CMOS and BiCMOS, SoI.	6 Lectures

Text Books:

1. Introduction to Semiconductor Materials and devices by M.S Tyagi, John Wiley & Sons, $5^{\rm th}$ Edition, 2005.

2. Semiconductor Devices: Modeling and Technology by A Dasgupta, N. Dasgupta, Prentice Hall of India Private Limited, 2004.

3. Solid State Physics by Neil W. Ashcroft, N. David Mermin, Cengage Learning, 2011.

Reference Books:

1. Physics of Semiconductor Devices by S. M. Sze and Kwok K. Ng, John Wiley & Sons, 3rd Edition, 2002.

2. Solid State Electronic Devices by Ben G. Streetman and Sanjay Banerjee, Prentice Hall, 6th Edition, 2005.

3. Semiconductor Device Fundamentals by Robert F. Pierret, Addison-Wesley Publishing, 1996

4. Semiconductor Physics and Devices by Donald A. Neamen, Mc GrawHill, 3rd Edition 2003

5. Semiconductor Devices- Basic Principles by Jasprit Singh, John Wiley and Sons Inc., 2001

6. Semiconductor Devices- Physics and Technology, by S. M. Sze and M.K. Lee, John Wiley & Sons, 3rd Edition, 2012.

Analog VLSI Circuits

L-T-P: 3-0-0	Credits: 6
1. Introduction: Basic MOSFET device, characteristics, second order effects, MOS device model.	6 Lectures
2. Amplifiers: Low frequency and high frequency operation of single stage amplifier and differential amplifier, (i) Single stage amplifiers: common source (CS), source follower, common gate stage, cascade stage with different load; (ii) Differential Amplifiers: Basic differential operation, common mode response, Current mirror, differential amplifier with current mirror load.	7 Lectures
3. Noise analysis: Statistical characteristic of noise, thermal noise, Flicker noise, representation noise in circuits	3 Lectures
4. Operational amplifier: one stage OPAMP, two stage OPAMP, gain boosting, common mode feedback, slew rate, power supply rejection.	3 Lectures
5. Bandgap references: Supply independent biasing, temperature independent references, PTAT and CTAT current generation	4 Lectures
6. Switched capacitor circuits: Sampling switches, switched capacitor amplifier, switched capacitor integrator.	3 Lectures
7. Oscillators: Feedback and Stability, Ring Oscillator, L-C oscillator, Voltage Control oscillator, phase locked loop, building blocks, locking characteristics and design.	5 Lectures
8. Comparator: Simple, Switch-based and latch based.	3 Lectures
9. Data Converter: Characterization of ADC and DAC, ADC and DAC architectures.	3 Lectures
10. Active Filters: Design of switch capacitor filer, Design of Gm-C filter.	3 Lectures

Text Books:

ECL 2102

1. Design of Analog CMOS Integrated Circuits by Behzad Razavi, McGraw Hill, 2003 2. CMOS Analog Circuit Design by P.E Allen and Douglas R. Holdberg, Oxford University Press, 2nd edition, 2012.

Reference Books:

1. Analysis and Design of Analog Integrated Circuits by Paul Gray and Robert G Meyer, John Wiley & Sons, 2009

2. Analog Circuit Design by Johan Huijsing Rudy van Plassche and Willy Sansen, Springer Science and Business Media, B.V.

ECL 2104 L-T-P: 3-0-0

Digital VLSI Circuits

Credits: 6

 1. Combinational logic design: Static CMOS design-complementary CMOS-static properties- complementary CMOS design-Power consumption in CMOS logic gates- dynamic or glitching transitions-Design techniques to reduce switching activity- Radioed logic-pass transistor logic- Differential pass transistor logic- Sizing of level restorer-Sizing in pass transistor-Dynamic CMOS design-Basic principles -Domino logic optimization of Domino logic-NPCMOS-logic style selection Designing logic for reduced supply voltages.

2. Sequential logic design: Timing metrics for sequential circuit latches Vs registers -static latches and registers - Bi-stability principle multiplexer based latches-master slave edge triggered registers- non-ideal clock signals low voltage static latches-static SR flip flop - Dynamic latches and registers-CMOS register - Dual edge registers-True single phase clocked registers-pipelining to optimize sequential circuit latch Vs register based pipelines-non-Bistable sequential circuit-Schmitt triggermono stable –Astable sequential circuit - choosing a clocking strategy.

3. CMOS subsystem design: Data Path **Operations: 12 Lectures** Addition/Subtraction - Comparators- Zero/One Detectors- Binary Counters- General arrangement of 4-bit Arithmetic Processor, Design of 4-bit shifter, Design of ALU subsystem, Implementing ALU functions with Carry-look-ahead adders, Multipliers, adder. Serial Parallel an multipliers, Pipeline multiplier array, modified Booth"s algorithm, Memory elements, control: Finite-State Machines.

4. HARDWARE MODELING WITH THE VERILOG HDL: Hardware
Encapsulation –The Verilog Module, Descriptive Styles, Structural
Connections, Behavioral Description In Verilog, Hierarchical Descriptions
of Hardware, Structured (Top Down) Design Methodology, Using Verilog
for RTL Synthesis.

Text Books:

1. CMOS VLSI Design –A Circuits and Systems Perspective by Neil H Weste, D Harris and Ayan Banerjee, Pearson, 2012.

2. Digital Integrated Circuits- A Design Perspective by J M Rabaey, Prentice Hall, 3rd Edition, 2012.

3. FPGA based systems, Waney Wolf, Pearson, 1st ed, 2005.

4. Sung-Mo Kang, Yusuf Leblebici, "CMOS Digital IC-Analysis and Design", Tata McGraw Hill publication.

Reference Books:

1. M. D. CILETTI, "Modeling, Synthesis and Rapid Prototyping with the Verilog HDL", Prentice-Hall.

2. M. G. ARNOLD, "Verilog Digital – Computer Design", Prentice-Hall.

ECL 2105	Semiconductor Device Modeling	
L-T-P: 3-0-0		Credits: 6

1.	Introduction:	Semiconductor,	Junctions and Overview	2 Lectures
-				

2. Two terminal MOS Structure: Introduction, Flat band voltage,
Potential Balance and charge balance, Effect of gate body voltage on surface condition, Accumulation and depletion, Inversion, CV Characteristics.

3. Three terminal MOS Structure: Introduction, Contacting the **6 Lectures** Inversion layer, The body effect, Regions of inversion, V CB control.

4. Four terminal MOS Structure: Introduction, Transistor region of operation, Complete all region model, Simplified all region models, Model based on Quasi-Fermi Potential, Regions of inversion in term of terminal voltages, strong inversion, weak inversion, moderate inversion, source referenced vs body referenced modeling, effective mobility, temperature effects.

5. Small Dimension Effects: Introduction, carrier velocity saturation, channel length modulation, charge sharing, drain induced barrier lowering, punch through, hot carrier effects, polysilicon depletion, quantum mechanical effects, DC gate current, junction leakage: band to band tunneling and GIDL, leakage currents.

6. Large signal modeling: Introduction, quasi static operation, terminal currents in quasi static operation, transit time under DC conditions, limitations of Quasi static model, non-quasi static modeling, extrinsic parasitic.

7. Small signal modeling: Introduction, low frequency small signal **6 Lectures** model, medium frequency small signal model, noise, all region models.

8. High frequency small signal models: Introduction, quasi-static **4 Lectures** model, y-parameter models, non quasi static models, high frequency noise.

Text Books:

1. Operation and modeling of the MOS transistor by Yannis Tsividis, Oxford University Press, 2011.

Reference Books:

1. Charge-Based MOS Transistor Modeling: The EKV Model for Low-Power and RF IC Design by Christian C. Enz, Eric A. Vittoz, Wiley, 2006.

2. Fundamental of Modern VLSI devices by Yuan Taur and Tak H. Ning, Cambridge University press, 2nd Edition, 1998.

ECP 2101 L-T-P: 0-0-3 As per syllabus. Analog VLSI Circuits Lab

Credits: 3

Syllabus of Second Semester

ECL 2201	VLSI Physical Design	
L-T-P: 3-0-0		Credits: 6
1. Introduction: VLSI Design Cycle, Styles, System Packaging Styles, Algorith	, Physical Design Cycle, Design hmic complexity and optimization	4 Lectures
2. Partitioning: Problem formulation algorithms, Kernighan-Lin Algorithm, Sin	n, Classification of Partitioning mulated Annealing.	4 Lectures
3. Floor planning: Problem formulation algorithms, Constraint based floor plann	n, Classification of floor planning ing, Rectangular dualization.	4 Lectures
4. Pin Assignment: Problem formut assignment algorithms, General and characteristics of the second	ulation, Classification of pin annel pin assignments.	5 Lectures
5. Placement: Problem formulation algorithms, Partitioning based placement	n, Classification of placement talgorithms.	5 Lectures
6. Global Routing and Detailed Ro formulation, Classification of global ro algorithms; Detailed Routing: Problem routing algorithms, Single layer routing a	uting: Global Routing: Problem uting algorithms, Maze routing n formulation, Classification of algorithms.	5 Lectures
7. Physical Design Automation of FPC Design cycle for FPGAs, Partitioning, Re Non-Segmented model, Routing Algorit Physical Design Automation of MCMs: Ir MCM Physical Design Cycle.	GAs: FPGA Technologies, Physical outing: Routing Algorithm for the thms for the Segmented Model; ntroduction to MCM Technologies,	7 Lectures
8. Chip Input and Output Circuits: Output Circuits and noise, On-chip clo	ESD Protection, Input Circuits, ock Generation and Distribution,	4 Lectures
9. On Chip PDN Design: Noise and Deca	ap Placement.	2 Lectures
Text Books: 1. Algorithms for VLSI Physical Desi International Edition, 3 rd Edition, 2005.	ign Automation by Naveed Shervar	ni, Springer

2. VLSI Physical Design Automation Theory and Practice by Sadiq M Sait, Habib Youssef, World Scientific.

3. FPGA based systems design, Waney Wolf, Pearson, 1st ed, 2005

Reference Books:

1. Algorithms for VLSI Design Automation, S. H. Gerez, 1999, Wiley student Edition, John Wiley and Sons (Asia) Pvt. Ltd.

2. VLSI Physical Design Automation by Sung Kyu Lim, Springer International Edition.

ECL 2202 IC Technology	
L-T-P: 3-0-0	Credits: 6
1. Introduction: Integrated Circuits and Planar Process, IC Families, CMOS Process Flow.	2 Lectures
2. Crystal Growth and Wafer Fabrication: Crystal Structure, Defects in Crystals, Raw materials and Purification, Czochralski and Float-Zone Crystal Growth Methods, Wafer Preparation and Specification, Measurement Methods.	6 Lectures
3. Lithography: Light Sources, Wafer Exposure Systems, Photoresists, Mask Engineering, Measurement of Mask Features and Defects, Resist Patterns and Etched Features	4 Lectures
4. Oxidation: Basic Concepts, Wet and Dry methods, Measurement Methods: Physical, Electrical and Optical, Models and Simulation: Linear and Parabolic, Growth Kinetics, Effect of Temperature, Pressure and Crystal Orientation	2 Lectures
5. Memory testing: Permanent, intermittent and pattern-sensitive faults;	5 Lectures
test generation. 6. Ion Implantation: Role of Crystal Structure, High-Energy Implants, Illtralow Energy Implants, Ion Beam Heating, Measurement Methods	2 Lectures
 Models: Nuclear Stopping, Electronic Stopping, Damage and annealing. 7. Deposition: Manufacturing Methods, CVD, APCVD, LPCVD, PECVD, PVD, Epitaxial Silicon, MBE, MOCVD, Polycrystalline Silicon, dielectrics and matala. Manufacturing metala. 	6 Lectures
8. Etching: Wet, Plasma Etching, Etching of Various Films, Measurement and Models.	4 Lectures
9. Back-end technology: Contacts, Interconnects and Vias, Silicide Gates and Source/Drain Regions, IMD Deposition and Planarization, Chemical-Mechanical Polishing, Electro-migration, Measurement methods and methods.	6 Lectures
10. Wafer Processing, Process Variation and DFM.	3 Lectures
Text Books: 1. Silicon VLSI Technology by James Plummer, M. Deal and P.Griffin Electronics and VLSI series, 2009.	, Prentice Hall

2. Semiconductor Devices: Basic Principles, Wiley Student edition, Paperback, 2007, Jasprit Singh.

3. VLSI Technology, by S M Sze, McGraw-Hill, 1988.

Reference Books:

1. The Science and Engineering of Microelectronics, by Stephen Campbell, Oxford University Press, 1996.

2. VLSI Fabrication Principles by Sorab K Ghandhi, John Wiley and Sons, 2nd Edition, 1994.

3. Microchip Fabrication by Peter van Zant, MicraGraw Hill, Sixth edition, 2013

ECL 2203	VLSI Testing and Verification	
L-T-P: 3-0-0		Credits: 6

1. Physical faults and their modeling: Automatic test pattern generation. Fault equivalence and dominance; fault collapsing, permanent	8 Lectures
and transient faults.	
2. Fault simulation: Parallel, deductive and concurrent techniques;	3 Lectures
critical path tracing.	
3. Test generation for combinational circuits: Boolean difference, D-	6 Lectures
algorithm, PODEM, Exhaustive, random and weighted test pattern	
generation; aliasing and its effect on fault coverage.	
4. PLA testing: Cross-point fault model, test generation, easily testable	4 Lectures
designs.	
5. Diffusion: Dopant Solid Solubility, Fick's Law, Predeposition and drive-	4 Lectures
in, Gaussian Solution near a Surface, Measurement Methods: SIMS,	
Spreading Resistance, Sheet Resistance, Capacitance Voltage.	
6. Test pattern generation for sequential circuits: Ad-hoc and	4 Lectures
structured techniques; scan path and LSSD, boundary scan.	
7. Design for testability, Built-in self-test techniques, System-on-chip	4 Lectures
(SoC) testing. Low-power testing. Delay fault testing. Idda testing.	
8. Design verification techniques based on simulation, analytical and	4 Lectures
formal approaches Functional verification. Timing verification. Formal	
verification	
9. Basics of equivalence checking and model checking Hardware	3 Lectures

9. Basics of equivalence checking and model checking. Hardware **3 Lectures** emulation

Text Books:

1. Design of analog CMOS integrated circuits by Behzad Razavi, McGraw-Hill, 2003.

2. CMOS circuit design, layout and simulation by R. Jacob Baker, Revised second edition, IEEE press, 2008.

3. CMOS Integrated ADCs and DACs by Rudy V. dePlassche, Springer (Indian edition), 2005.

4. A roadmap for formal property verification, Pallab Das Gupta, Springer, 1st ed, 2006 with NPTEL lectures.

5. Essentials of electronic testing for digital, memory and mixed signal VLSI circuits, M L Bushnell and V D Agarwal, Springer, 1^{st} ed, 2002

Reference Books:

1. VLSI Physical Design Automation Theory and Practice by Sadiq M Sait, Habib Youssef, World Scientific.

ECP 2201 L-T-P: 0-0-3	Digital VLSI Circuits Lab	Credits: 3
As per syllabus.		

ECP 2202	Device and Process Modeling Lab
L-T-P: 0-0-3	

Credits: 3

As per syllabus.

ECP 2203	VLSI System Design Lab
L-T-P: 0-0-3	

Credits: 3

Areas to be considered:

Analog Design: OPAMP, ADC, Ring VCO, LC VCO Digital Design & FPGA: DFT, FFT, ALU, Memory Tools: Analog: Cadence & Synopsis Digital: Synopsis & Xilinx

For Analog & Digital Design (except FPGA), the students should perform schematic level design, process corner simulation and temperature variation simulation, layout and post layout simulation.

For FPGA Design: Simulation, RTL Synthesis and FPGA Hardware Implementation.

Third Semester

ECP 2301 L-T-P: 0-0-16 **Project Phase I**

Credits: 16

Fourth Semester

ECP 2401 L-T-P: 0-0-24 **Project Phase II**

Credits: 24

Syllabus of Electives

ECL 21XX/22XX	Mixed Signal VLSI Design	
L-T-P: 3-0-0		Credits: 6
1. Introduction: Signals, Filters and T Filters, Representing Signals, Sampling an	ools: Sinusoidal Signals, Comb nd Aliasing.	4 Lectures
2. Filters: Continuous-time filters, Dis discrete-time signal processing, Analog in discrete-time (switched-capacitor) filters.	screte-time filters, Analog and ntegrated continuous-time and	6 Lectures
3. Digital Converters: Basics of Anala Basics of Digital to analog converte approximation ADCs, Dual slope ADCs, pipeline ADC and related architectures sigma converters.	og to digital converters (ADC), ers (DAC), DACs, Successive , High-speed ADCs: flash ADC, , High-resolution ADCs: delta-	8 Lectures
4. Phase locked loops: Phase Detector Vo Filter: XOR DPLL, PFD DPLL, System ONRZ Data, Delay-Locked Loops.	oltage Controller Oscillator, Loop Concerns: Clock Recovery From	6 Lectures
5. VLSI Layout: Chip Layout: Regularity, and Ground Considerations, Layout Sterand Stick Diagrams, Device Placement, Full-Custom Layout.	, Standard Cell Examples, Power ps by Dean Moriarty: Planning Polish, Standard cells Versus	8 Lectures
6. Interconnects: Basics, application, RC	C delay and its model.	6 Lectures

Text Books:

1. CMOS mixed-signal circuit design by R. Jacob Baker, Wiley India, IEEE press, 2008.

Reference Books:

1. Design of analog CMOS integrated circuits by Behzad Razavi, McGraw-Hill, 2003.

2. CMOS circuit design, layout and simulation by R. Jacob Baker, Revised second edition, IEEE press, 2008.

3. CMOS Integrated ADCs and DACs by Rudy V. dePlassche, Springer (Indian edition), 2005.

4. Electronic Filter Design Handbook by Arthur B. Williams, McGraw-Hill, 1981.

5. Design of analog filters by R. Schauman, Prentice-Hall 1990.

ECL 21XX/22XX L-T-P: 3-0-0

Low Power VLSI Design

Credits: 6

1. Introduction: Low power and its applications; Algorithmic, **6 Lectures** Architectural, Gate and Physical Level power reduction approaches.

2. Sources of Power Dissipation: Dynamic Power Dissipation: Short
 8 Lectures
 8 Lectures
 9 Dissipation, Degrees of Freedom.

3. Supply Voltage Scaling Approaches: Device feature size scaling,
 8 Lectures Multi-Vdd Circuits, Voltage scaling using high-level transformations,
 Dynamic voltage scaling, Power Management.

4. Switched Capacitance Minimization Approaches: Hardware **8 Lectures** Software Tradeoff, Bus Encoding Two's complement verses Sign Magnitude, Clock Gating.

5. Leakage Power minimization Approaches: Variable-threshold-voltage **6 Lectures** CMOS (VTCMOS) approach, Multi-threshold-voltage CMOS (MTCMOS) approach, Power gating, Transistor stacking, Dual-Vt assignment approach (DTCMOS).

6. Low Power Design Examples: Memory, Arithmetic circuits. 4 Lectures

Text Books:

1. Low Power VLSI CMOS Circuit Design, by A. Bellamour, and M. I. Elmasry, Springer Science + Business Media, 2012.

2. Low Power Design Essentials (Integrated Circuits and Systems), by Jan Rabaey, Springer, 2009.

Reference Books:

1. Principles of CMOS VLSI Design, by Neil H. E. Weste and K. Eshraghian, Addison Wesley (Indian reprint).

CMOS Digital Integrated Circuits, by Sung Mo Kang, Yusuf Leblebici, Tata McGraw Hill.
 Low Power Digital CMOS Design, by Anantha P. Chandrakasan and Robert W. Brodersen, Kluwer Academic Publishers, 1995.

4. Low Power CMOS VLSI circuit design by Kaushik Roy, Sharat C. Prasad, John Willy & Sons, 2009.

ECL 21XX/22XX MEMS and Microsystems	
L-T-P: 3-0-0	Credits: 6
 Scaling Laws, Why MEMS? Micro-fabrication Techniques: Bulk micro machining, surface micro machining and LIGA processes 	2 Lectures 6 Lectures
3. MEMS based inertial sensors: Accelerometer; piezo-resistive and capacitive.	6 Lectures
 4. MEMS based gyro and tilt sensors 5. MEMS based pressure sensor: (Type Pressure Monitoring System) 6. Electrostatic actuation: study of electrostatically actuated micromachined cantilever beam: Free natural mode of vibration, resonance analysis, static voltage response, pull in and pull out phenomenon. Dynamic response to time varying electrostatic actuation 	2 Lectures 2 Lectures 4 Lectures
7. RF MEMS: RF switch, MEMS based inductor and capacitors, MEMS based varactors and resonators.	6 Lectures
 8. Optical MEMS: MEMS based mirrors, MEMS based optical switch 9. Microfluidic and Bio MEMS: advantages of MEMS based fluidic system. 10. Micro pump and Micro valve, Micro nozzle and thrusters, micro needle, micro cantilever based bio sensors, lab on a chip. 11. MEMS based interfacing electronics: variable gain instrumentation amplifier and wireless integrated micro sensors. 	2 Lectures1 Lectures6 Lectures4 Lectures

Text Books:

1. Analysis and design principles of MEMS devices by M.-H. Bao.

2. Microsystem Design by Stephen D. Senturia, Kluwer Academic Publishers, 2001.

3. Micro and Smart system by G. K. Ananthasuresh, K.J. Vinoy, S. Gopalakrishnan, K. N. Bhat, V. K. Aatre, Wiley, 2012.

4. Fundamentals of Microfabrication techniques, Marc Madou, CRC Press

ECL 21XX/22XX VLSI Architect	ure for DSP
L-T-P: 3-0-0	Credits: 6
1. Introduction: Introduction to DSP systems, DSP ap and scaled CMOS technologies, representation of DSP alg FFT.	plication demand 3 Lectures orithms, DFT and
2. Iteration bound: Introduction, data flow graph repr	esentations, loop 4 Lectures
bound and iteration bound, algorithms for computing itera	tion bound.
3. Pipelining and parallel processing: Introduction,	pipelining of FIR 5 Lectures
digital filters, parallel processing, pipelining and parallel p	processing for low
power.	-
4. Retiming: Introduction, properties, solving systems	of inequalities, 6 Lectures
retiming techniques.	-
5. Unfolding: Introduction, algorithm for unfolding, p	roperties, critical 6 Lectures
path, unfolding and retiming, applications.	• <i>· ·</i>
6. Folding: Introduction, folding transformation, regis	ter minimization 6 Lectures
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techniques, register minimization in folded architectures. **7. Systolic Architecture Design:** Introduction, systolic array design **4 Lectures** methodology, FIR systolic arrays, scheduling vector, matrix multiplication and 2D systolic array design.

8. Bit level arithmetic architectures: Introduction, parallel multipliers, **4 Lectures** bit serial multipliers, bit serial filter design and implementation, canonic signed digit arithmetic, distributed arithmetic.

9. Redundant Arithmetic: Introduction, Redundant number **4 Lectures** representation, carry free radix-2 additions and subtractions, hybrid radix-4 addition, radix-2 hybrid redundant multiplication architecture, data format conversion.

Text Books:

1. VLSI digital signal processing systems by K K Parhi, John Wiley & Sons, 1999.

Reference Books:

1. DSP with FPGA by U. Meyer-Baese, Springer, 2004.

M.Tech Programme in Microelectronics & VLSI System Design: Course Structure & Syllabus

ECL 21XX/22XX Embedded Systems	
L-T-P: 3-0-0	Credits: 6
1. Introduction: Features, Design metrics, Design flow. 2. ARM Microcontroller: ARM Instruction set architecture, ARM pipeline, THUMB instructions, Exceptions in ARM.	2 Lectures 5 Lectures
3. Digital Signal Processors: Architecture, Data access features, Computation features, Accuracy, C6000 family of DSP.	4 Lectures
4. Field Programmable Gate Arrays: Field programmable devices, Programmability, Logic block variations, Design flow, Modern FPGAs, Concept of soft and hard IP.	5 Lectures
5. Interfacing: Requirements, SPI, IIC, RS232-C family, USB, IrDA, CAN,	7 Lectures
 Bluetooth, PCI 6. Real-time System Design: Task classification, Periodicity, Task scheduling, Scheduling algorithms, Resource sharing, Commercial RTOS. 7. Hardware-Software Codesign: Introduction to specification, partitioning 	8 Lectures 5 Lectures
and cosimulation. 8. Case studies: Example embedded system design, such as digital camera	4 Lectures

Text Books:

etc.

Embedded System Design, by S. Chattopadhyay, 2nd Edition, 2014.
 Embedded System Design: A Unified Hardware/Software Introduction, 2002.

Reference Books:

1. Embedded System Design, P. Marwedel, 2003.

ECL 21XX/22XX
L-T-P: 3-0-0

RF IC Design

Credits: 6

1.	Introduction	to	RF	and	Wireless	Technology:	Complexity,	design	2]	Lectures
an	d applications.	Ch	oice	of Te	chnology.					

2. Basic concepts in RF Design: Nonlinearly and Time Variance, intersymbol Interference, random processes and Noise. Definitions of sensitivity and dynamic range, conversion Gains and Distortion.

3. Analog and Digital Modulation for RF circuits: Comparison of **10 Lectures** various techniques for power efficiency. Coherent and Non coherent defection. Mobile RF Communication systems and basics of Multiple Access techniques. Receiver and Transmitter Architectures and Testing heterodyne, Homodyne, Image-reject, Direct-IF and sub-sampled receivers. Direct Conversion and two steps transmitters. BJT and MOSFET behavior at RF frequencies Modeling of the transistors and SPICE models. Noise performance and limitation of devices. Integrated Parasitic elements at high frequencies and their monolithic implementation.

4. Basic blocks in RF systems and their VLSI implementation: Low
Noise Amplifiers design in various technologies, Design of Mixers at GHz frequency range. Various Mixers, their working and implementations.

5. Oscillators: Basic topologies VCO and definition of phase noise. Noise-Power trade-off. Resonator-less VCO design. Quadrature and singlesideband generators.

6. Radio Frequency Synthesizers: PLLS, design of integer-N RF **5 Lectures** frequency synthesizer and frequency dividers.

7. Design issues in integrated RF filters: Some discussion on available4 LecturesCAD tools for RF VLSI designs; Prerequisite: (Analog VLSI Design).

8. RF power amplifier and linearization techniques: Classification of **3 Lectures** power amplifiers, design of class AB and class E amplifier, various techniques of linearization in cartesian mode

Text Books:

1. RF Microelectronics by B Razavi, Prentice-Hall PTR, 1998.

2. The Design of CMOS Radio-Frequency Integrated Circuits, by T H Lee, Press, 1998.

3. Power Amplifier by Cripp

Reference Books:

1. CMOS Circuit Design, Layout and Simulation, by R J Baker, H W Li, and D.E. Boyce, Prentice-Hall, 1998.

2. Mixed Analog and Digital VLSI Devices and Technology by Y P Tsividis, McGraw Hill, 1996.

ECL 21XX/22XX
L-T-P: 3-0-0

Nano-and-Molecular Electronics

Credits: 6

 Introduction: Nanotechnology and Nanoelectronics; Moore's Law;
 Review of Semiconductor Electronics: Maxwell's Equation, Poisson Equation, Continuity Equations, carrier concentration, Carrier Transport, Drift and diffusion; basics of molecular electronics.

2. Basics of Quantum Mechanics: Photoelectric effect; Wave nature of particles and wave-particle duality; Compton Effect; Uncertainty Principle; Schrodinger's equations and its applications; Wave function and postulates; Pauli-exclusion principle; Quantum dots, wires, and wells; Transport in quantum structures; Optoelectronic property.

3. Nanoelectronic Devices: Overview of MOS and MOSFET; CMOS **10 Lectures** Scaling and shrink down approaches; FINFET; Tunnel FET; Junctionless Transistor; Single electron transistors; Nanowire MOSFET, GAA FET.

4. Molecular Electronics: Need of molecular electronics and atoms-up approach; Strategies of electronic development; Molecular bonding and hybridization; Molecules as electronic devices; Carbon molecules & electronics; Pentacene; Transport in molecular electronics; Graphene devices; Carbon nanotube electronics; CNT FET.

Text Books:

1. C.P. Poole Jr. and F.J. Owens, Introduction to Nanotechnology, Wiley, 2003.

- 2. D.A. Neamen, Semiconductor Physics & Devices, TMH, 2003.
- 3. Ashcroft and Mermin, Solid State Physics, Thomson Press (India) Ltd, 2003.
- 4. G.W. Hanson, Fundamentals of Nanoelectronics, Pearson, 2009.
- 5. M.C. Petty, Molecular Electronics: From Principles to Practice, Wiley, 2007.

Reference Books:

1. C. Kittel, Introduction to solid state physics, Wiley, New York, 1976.

2. K. Iniewski, Nanoelectronics : nanowires, molecular electronics, and nanodevices, Mc Graw Hill, New York, 2011.

- 3. K. Sienicki, Molecular Electronics and Molecular Electronic Devices, CRC Press, 1994.
- 4. S.M. Sze, Physics of Semiconductor Devices, Wiley, New York, 1981.

5. J.H. Davies, The Physics of Low-Dimensional Semiconductors, Cambridge University Press, 1998.

- 6. R.F. Pierrett, Semiconductor Device Fundamentals, Pearson, 2006.
- 7. B.G. Streetman and S. Banerjee, Solid State Electronic Devices, Pearson, 2008.